



HMBTA64

PNP SILICON TRANSISTOR

Description

The HMBTA64 is designed for application requiring extremely high current gain at collector current to 500mA.

Features

- High D.C. Current Gain
- For Complementary use with NPN Type HMBTA14

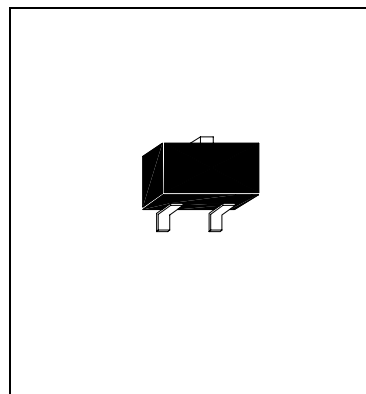
Absolute Maximum Ratings

- Maximum Temperatures
Storage Temperature..... -55 ~ +150 °C
Junction Temperature..... +150 °C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Ta=25°C) 225 mW
- Maximum Voltages and Currents (Ta=25°C)
VCBO Collector to Base Voltage -30 V
VCES Collector to Emitter Voltage -30 V
VEBO Emitter to Base Voltage -10 V
IC Collector Current -500 mA

Characteristics (Ta=25°C)

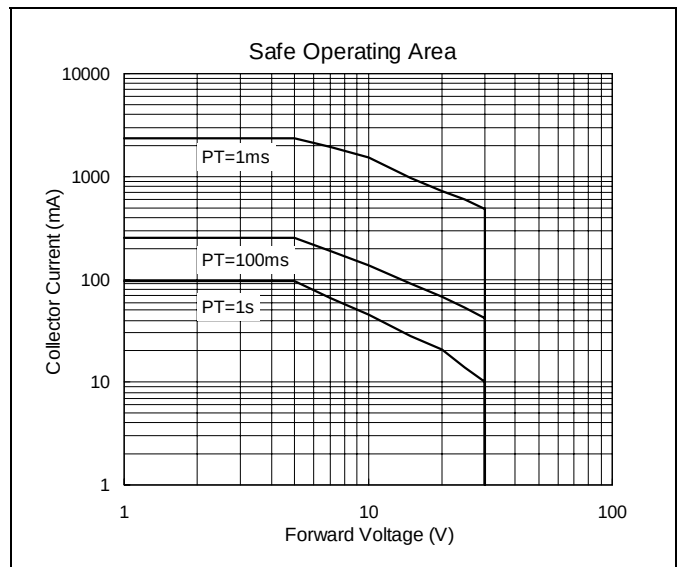
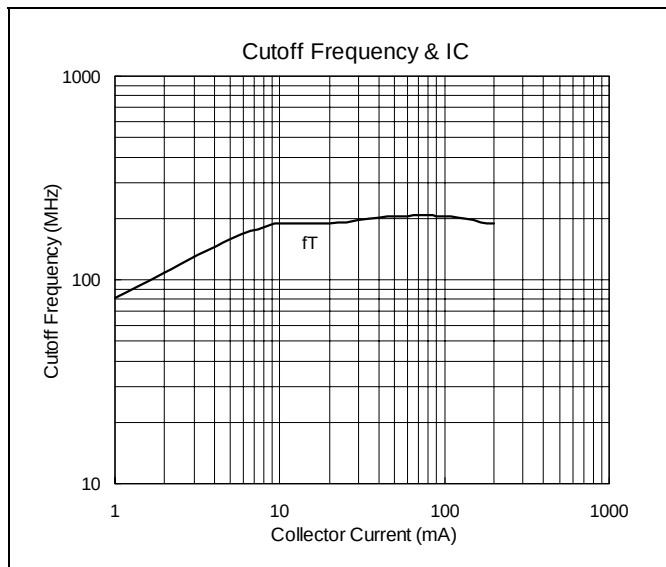
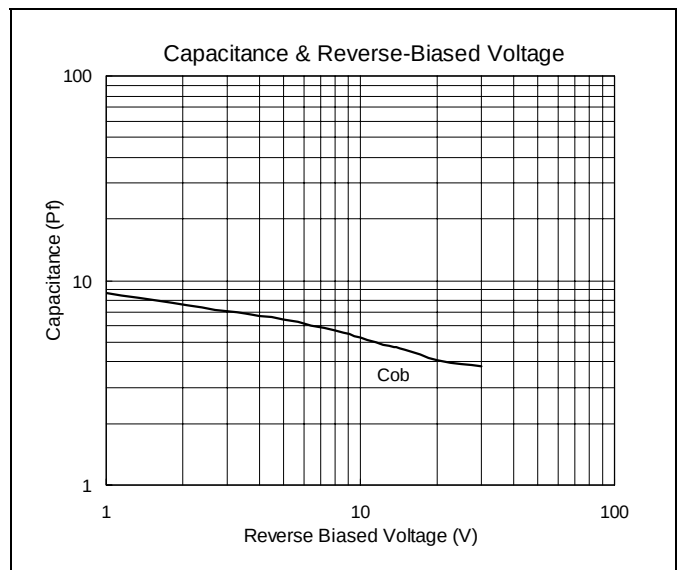
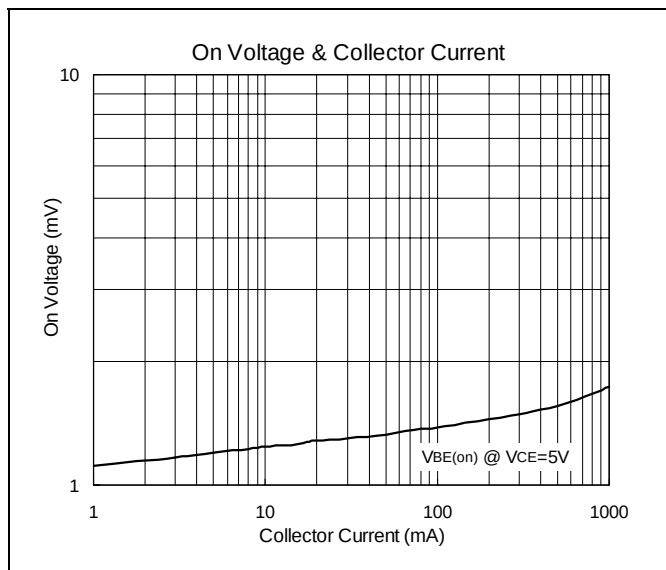
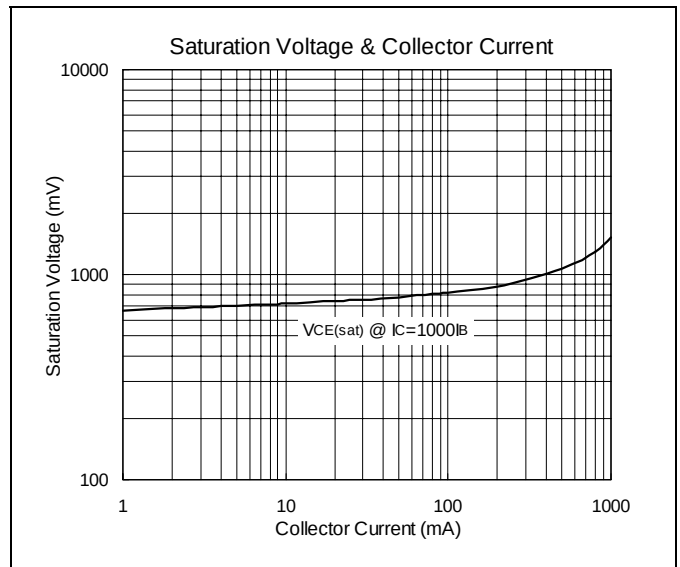
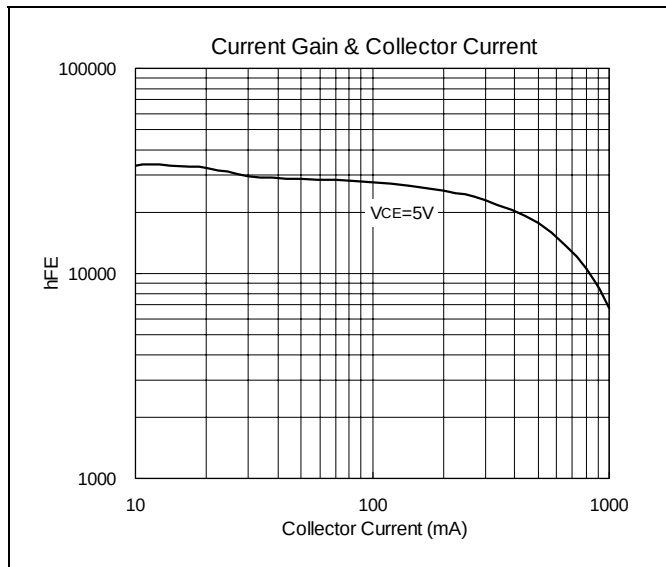
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-30	-	-	V	IC=-100uA
BVCES	-30	-	-	V	IC=-100uA
BVEBO	-10	-	-	V	IE=-10uA
ICBO	-	-	-100	nA	VCB=-30V
IEBO	-	-	-100	nA	VEB=-10V
*VCE(sat)	-	-	-1.5	V	IC=-100mA, IB=-0.1mA
VBE(on)	-	-	-2	V	IC=-100mA, VCE=-5V
*hFE1	10K	-	-		IC=-10mA, VCE=-5V
*hFE2	20K	-	-		IC=-100mA, VCE=-5V
fT	125	-	-	MHz	IC=-100mA, VCE=-5V, f=100MHz

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%



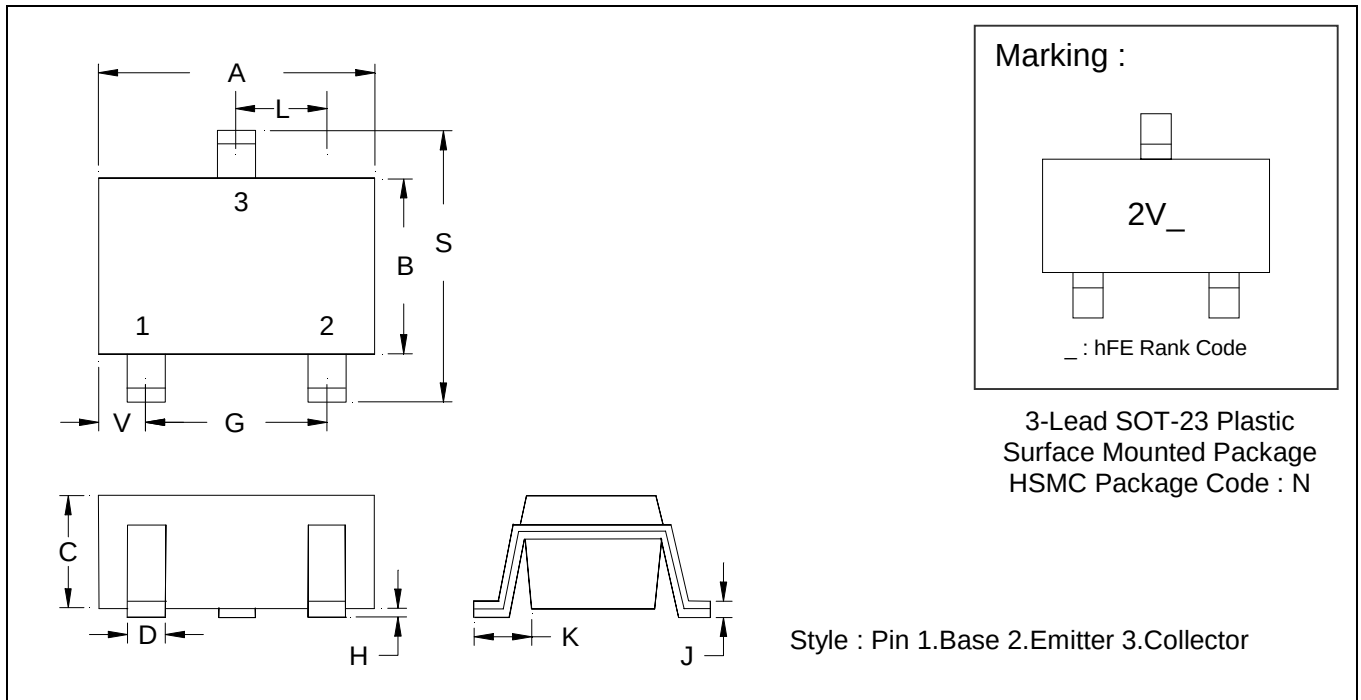


Characteristics Curve





SOT-23 Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1102	0.1204	2.80	3.04	J	0.0034	0.0070	0.85	0.177
B	0.0472	0.0630	1.20	1.60	K	0.0128	0.0266	0.32	0.67
C	0.0335	0.0512	0.89	1.30	L	0.0335	0.0453	0.85	1.15
D	0.0118	0.0197	0.30	0.50	S	0.0830	0.1083	2.10	2.75
G	0.0669	0.0910	1.70	2.30	V	0.0098	0.0256	0.25	0.65
H	0.0005	0.0040	0.013	0.10					

Notes : 1.Dimension and tolerance based on our Spec. dated Sep. 07,1997.

2.Controlling dimension : millimeters.

3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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